



TESSERA 3.0-078 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#6/B
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Full

In re Patent Applicant of
Joseph Fjelstad

Group Art Unit: 2811

Application Serial No. 09/020,647 ✓

Examiner: Unassigned

Filed: February 9, 1998

Date: May 1, 1998

For: **METHOD OF MAKING A
SEMICONDUCTOR CHIP PACKAGE**

X

Assistant Commissioner For Patents
Washington, D.C. 20231

MAY 07 1998

SUPPLEMENTAL PRELIMINARY AMENDMENT

Sir:

Further to the Preliminary Amendment filed February 9, 1998, please
amend the above-identified application as follows:

In the Claims:

Add new claims 21-34 as follows:

21. A method of making a compliant microelectronic assembly
comprising the steps of:
providing a microelectronic element having a first surface and a plurality
of contacts disposed on the first surface thereof;
providing a compliant layer over the first surface of said microelectronic
element, said compliant layer having a bottom surface facing toward said first surface
of said microelectronic element, a top surface facing upwardly away from said

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Class mail in an envelope addressed to Assistant Commissioner for
Patents, Washington, D.C. 20231 on May 1, 1998.

Michael J. Doherty

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MICHAEL J. DOHERTY

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